HBL21000RP

Product Preview

1-Channel ESD Protector

Product Description

The HBL21000RP provides robust ESD protection for sensitive parts that may be subjected to electrostatic discharge (ESD). The tiny form factor and single wirebond requirement enables it to be used in very confined spaces. The electrical 'back-to-back zener' configuration also provides ESD protection in cases where nodes with AC signals are present. This device is designed and characterized to safely dissipate ESD strikes of at least ±8 kV, according to the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD.

Features

- Compact Die Protects from ESD Discharges
- Almost No Conduction at Signal Amplitudes Less Than ±4 V
- ESD Protection Over ±8 kV Contact Discharge per MIL_STD_883
 International ESD Standard

Applications

- LED Lighting
- Modules
- Interface Circuits

Aluminum (Al) Pad on the Topside



Gold-Tin (AuSn) on the Backside

Figure 1. Electrical Schematic



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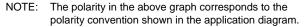
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ORDERING INFORMATION

HBL21000RP

CURRENT/VOLTAGE GRAPH

| Symbol | Description |
|------------------|--------------------------------------|
| I _{CL+} | Positive Clamping Current |
| V _{CL+} | Positive Clamping Voltage |
| I _{L2+} | Leakage Current at V _{L2+} |
| V _{L2+} | Voltage Condition: +14V |
| I _{L1+} | Leakage Current at V _{L1+} |
| V _{L1+} | Voltage Condition: +4V |
| I _{CL} | Negative Clamping Current |
| V _{CL} | Negative Clamping Voltage |
| I _{L1-} | Leakage Current at V _{L1} _ |
| V _{L1-} | Voltage Condition: -4V |



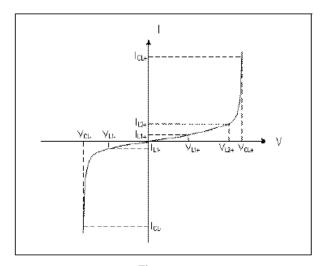


Figure 2.

ORDERING INFORMATION

| Ordering Part Number | Topside Metal | Backside Metal | Thickness | Shipping Method |
|----------------------|---------------|----------------|-----------|-----------------|
| HBL21000RP | Al | AuSn | 4 mils | Ring Pack |

ABSOLUTE MAXIMUM RATINGS

| Parameter | Rating | Unit |
|-----------------------------|-------------|------|
| Operating Temperature Range | -40 to +150 | °C |
| Storage Temperature Range | -65 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

STANDARD OPERATING CONDITIONS

| Parameter | Rating | Unit |
|-----------------------------|-------------|------|
| Operating Temperature Range | -40 to +150 | °C |

HBL21000RP

ELECTRICAL OPERATING CHARACTERISTICS (See Note 1)

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Unit |
|-------------------|--|---|-------------|-------------|---|----------------|
| I _{LEAK} | Leakage Current | $V = \pm 4 \text{ V}, 150^{\circ}\text{C (Note 2)}$ $V = \pm 4 \text{ V}, 25^{\circ}\text{C (V}_{L1\pm})$ $V = +14 \text{ V}, 25^{\circ}\text{C (V}_{L2+})$ | | | 4.0 0.3 (I _{L1±}) 0.5 (I _{L2+}) | mA μA μA |
| V _{CL} | Signal Clamp Voltage Positive polarity on signal node (V _{CL+}) Negative polarity on signal node (V _{CL-}) | $T_A = 25$ °C; at 10 mA (I_{CL+}) at –10 mA (I_{CL-}) | +16 -9.0 | +19 -7.0 | +22 -5.0 | V |
| V _{ESD} | ESD Protection – withstand voltage: Human Body Model (MIL–STD–883, Method 3015) | T _A = 25°C (Note 2) | ±8 | | | kV |

- 1. Operating characteristics are over standard operating conditions unless otherwise specified.
- 2. This parameter is guaranteed by design and/or characterization.

MECHANICAL DETAILS

MECHANICAL SPECIFICATIONS

| Parameter | Condition | Unit |
|------------------------|----------------------------|------|
| Composition | Silicon wafer, p+ doped | |
| Die shape | Square | |
| Length (sawn) | 200 | μm |
| Width (sawn) | 200 | μm |
| Thickness | 4 | mils |
| Top pad length | 125 | μm |
| Top pad width | 125 | μm |
| Top pad composition | Al (Aluminum) | |
| Back metal (underside) | AuSn (Gold-Tin) | |

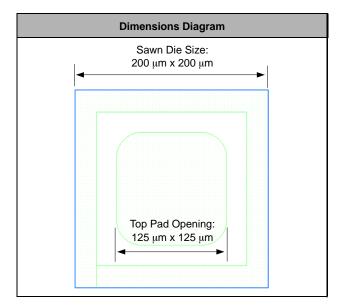


Figure 3. Die Dimensions

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